

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																				
NATURE OF CONVEYANCE:	ASSIGNMENT																				
<b>CONVEYING PARTY DATA</b>																					
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jia-Jia Chen</td> <td>08/21/2012</td> </tr> <tr> <td>Chi-Mao Hsu</td> <td>08/21/2012</td> </tr> <tr> <td>Tsun-Min Cheng</td> <td>08/21/2012</td> </tr> <tr> <td>Ching-Wei Hsu</td> <td>08/21/2012</td> </tr> <tr> <td>Szu-Hao Lai</td> <td>08/21/2012</td> </tr> <tr> <td>Huei-Ru Tsai</td> <td>08/21/2012</td> </tr> <tr> <td>Tsai-Yu Wen</td> <td>08/21/2012</td> </tr> <tr> <td>Ching-Li Yang</td> <td>08/21/2012</td> </tr> <tr> <td>Chien-Li Kuo</td> <td>08/21/2012</td> </tr> </tbody> </table>		Name	Execution Date	Jia-Jia Chen	08/21/2012	Chi-Mao Hsu	08/21/2012	Tsun-Min Cheng	08/21/2012	Ching-Wei Hsu	08/21/2012	Szu-Hao Lai	08/21/2012	Huei-Ru Tsai	08/21/2012	Tsai-Yu Wen	08/21/2012	Ching-Li Yang	08/21/2012	Chien-Li Kuo	08/21/2012
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<b>RECEIVING PARTY DATA</b>																					
Name:	UNITED MICROELECTRONICS CORP.																				
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park																				
City:	Hsin-Chu City																				
State/Country:	TAIWAN																				
<b>PROPERTY NUMBERS Total: 1</b>																					
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13593517</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13593517																
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Application Number:	13593517																				
<b>CORRESPONDENCE DATA</b>																					
Fax Number:	7039974517																				
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ATTORNEY DOCKET NUMBER:	NAUP1514USA
NAME OF SUBMITTER:	SIBYL YU
Total Attachments: 3 source=1447562#page1.tif source=1447562#page2.tif source=1447562#page3.tif	

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Jia-Jia Chen Nationality: TW

Name: Chi-Mao Hsu Nationality: TW

Name: Tsun-Min Cheng Nationality: TW

Name: Ching-Wei Hsu Nationality: TW

Name: Szu-Hao Lai Nationality: TW

Name: Huei-Ru Tsai Nationality: TW

Name: Tsai-Yu Wen Nationality: TW

Name: Ching-Li Yang Nationality: TW

Name: Chien-Li Kuo Nationality: TW

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"THROUGH SILICON VIA PROCESS"

Which is found in :

- (a)  U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_
- (e) \_\_\_\_\_ International application no. \_\_\_\_\_

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this AUG 21 2012 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Jia-Jia Chen

Jia-Jia Chen

Chi-Mao Hsu

Chi-Mao Hsu

Tsun-Min Cheng

Tsun-Min Cheng

Ching-Wei Hsu

Ching-Wei Hsu

Szu-Hao Lai

Szu-Hao Lai

Huei-Ru Tsai

Huei-Ru Tsai

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